imall

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4.7mm HOUSING FOR LED LAMP WITH WIRE



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Part Number: WP1533AA/ID14V-W152

High Efficiency Red

Features

- Outstanding material efficiency.
- Reliable and rugged.
- Low current capability.
- Housing UL rating: 94V-0.
- Housing material: type 66 nylon.
- 14V internal resistor.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

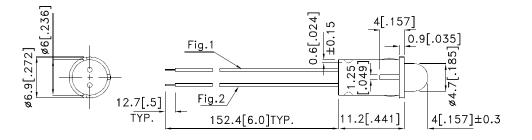
Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions

Fig.1 : ANODE LEAD :RED INSULATION LEAD ,24 AWG ,UL#1007,Ø1.45mm, TINNED OVERCOATED WIRE , STRIP 12.7mm. Fig. 2 : CATHODE LEAD :BLACK INSULATION LEAD ,24 AWG,UL#1007 ,Ø1.45mm, TINNED OVERCOATED WIRE , STRIP 12.7mm. Fig.3 : STAKING TO FIX THE HOLDER AND LED .



Remark: Recommended panel mount hole diameter ϕ =6.30-6.35mm; panel thickness 1.0mm.

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] V= 14V		Viewing Angle [1]
			Min. Ty		201/2
WP1533AA/ID14V-W152	High Efficiency Red (GaAsP/GaP)	Red Diffused	15	50	60°
			*8	*25	

Notes:

1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 Luminous intensity/ luminous Flux: +/-15%.
 * Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	VF=14V
λD [1]	Dominant Wavelength	High Efficiency Red	617		nm	VF=14V
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	VF=14V
lf	Forward Current	High Efficiency Red	10.5	13.5	mA	VF=14V
IR	Reverse Current	High Efficiency Red		10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm.

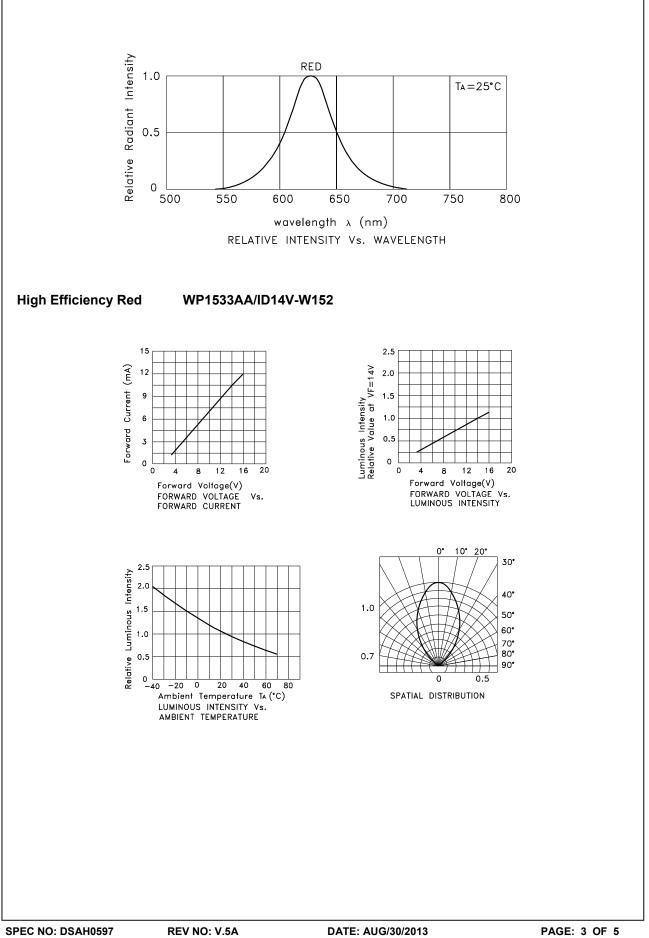
2. Wavelength value is traceable to the CIE127-2007 compliant national standards.

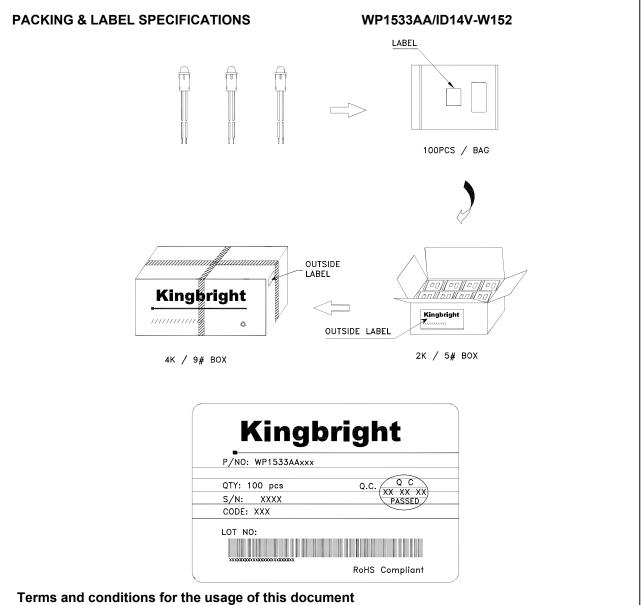
Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Units		
Power dissipation	160	mW		
Forward Voltage	16	V		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +70°C			
Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [1]	260°C For 3 Seconds			
Lead Solder Temperature [2]	260°C For 5 Seconds			

Notes:

2. 5mm below package base.
 2. 5mm below package base.

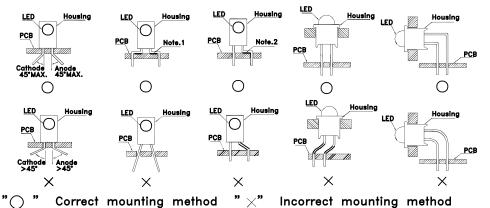




- 1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- 4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
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- 6.All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

PRECAUTIONS

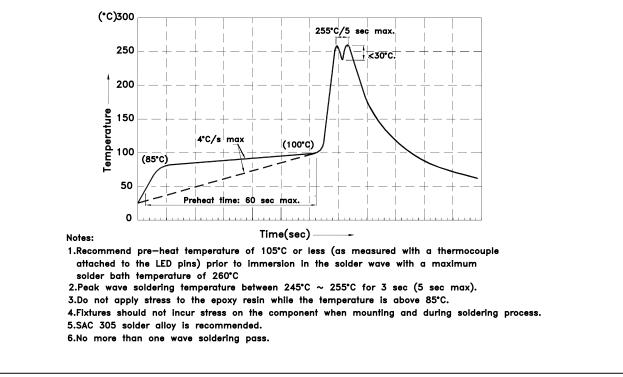
1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through-hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 6. Recommended Wave Soldering Profiles:



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